PD - 93764

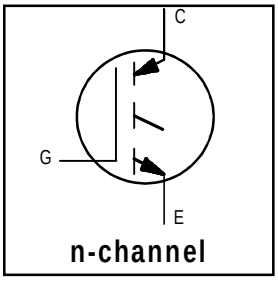
International
IOR Rectifier

PRELIMINARY

TO-263 IRG4BH20K-S,
TO-262 IRG4BH20K-L

INSULATED GATE BIPOLAR TRANSISTOR

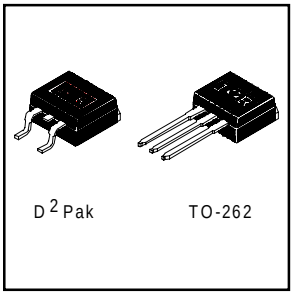
Short Circuit Rated
UltraFast IGBT



V_{CES} = 1200V

$V_{CE(on)\ typ.}$ = 3.17V

@V_{GE} = 15V, I_C = 5.0A



Features

- Very low turn off losses
- High short circuit rating optimized for motor control, t_{sc} =10µs, V_{CC} = 720V , T_J = 125°C, V_{GE} = 15V
- Combines low conduction losses with high switching speed
- Latest generation design provides tighter parameter distribution and higher efficiency than previous generations
- Surface Mount D^2Pak (IRG4BH20KS)
- Low-profile through-hole TO-262 (IRG4BH20KL)

Benefits

- Very small size, especially compared to similar performing MOSFETs
- As a Freewheeling Diode we recommend our HEXFRED™ ultrafast, ultrasoft recovery diodes for minimum EMI / Noise and switching losses in the Diode and IGBT
- Latest generation 4 IGBT's offer highest power density motor controls possible

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	1200	V
I_C @ T_C = 25°C	Continuous Collector Current	11	A
I_C @ T_C = 100°C	Continuous Collector Current	5.0	
I_{CM}	Pulsed Collector Current ①	22	
I_{LM}	Clamped Inductive Load Current ②	22	
t_{sc}	Short Circuit Withstand Time	10	µs
V_{GE}	Gate-to-Emitter Voltage	±20	V
E_{ARV}	Reverse Voltage Avalanche Energy ③	130	mJ
P_D @ T_C = 25°C	Maximum Power Dissipation	60	W
P_D @ T_C = 100°C	Maximum Power Dissipation	24	
T_J	Operating Junction and	-55 to +150	°C
T_{STG}	Storage Temperature Range Soldering Temperature, for 10 sec.*	300 (0.063 in. (1.6mm) from case)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	2.1	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.5	—	
$R_{\theta JA}$	Junction-to-Ambient (PCB Mounted,steady-state)*		40	
$R_{\theta JA}$	Junction-to-Ambient	—	80	
Wt	Weight	2.0(0.07)	—	g (oz)

8/17/99

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	1200	—	—	V	V_{GE} = 0V, I_C = 250µA
$V_{(BR)ECS}$	Emitter-to-Collector Breakdown Voltage ④	18	—	—	V	V_{GE} = 0V, I_C = 1.0A
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	1.13	—	V/°C	V_{GE} = 0V, I_C = 2.5mA
$V_{CE(ON)}$	Collector-to-Emitter Saturation Voltage	—	3.17	4.3	V	I_C = 5.0A V_{GE} = 15V
		—	4.04	—		I_C = 11A See Fig.2, 5
		—	2.84	—		I_C = 5.0A , T_J = 150°C
$V_{GE(th)}$	Gate Threshold Voltage	3.5	—	6.5		V_{CE} = V_{GE}, I_C = 250µA
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-10	—	mV/°C	V_{CE} = V_{GE}, I_C = 1mA
g_{fe}	Forward Transconductance ⑤	2.3	3.5	—	S	V_{CE} = 100 V, I_C = 5.0A
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	µA	V_{GE} = 0V, V_{CE} = 1200V
		—	—	2.0		V_{GE} = 0V, V_{CE} = 10V, T_J = 25°C
		—	—	1000		V_{GE} = 0V, V_{CE} = 1200V, T_J = 150°C
I_{GES}	Gate-to-Emitter Leakage Current	—	—	±100	nA	V_{GE} = ±20V

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	28	43	nC	I_C = 5.0A
Q_{ge}	Gate - Emitter Charge (turn-on)	—	4.4	6.6		V_{CC} = 400V See Fig.8
Q_{gc}	Gate - Collector Charge (turn-on)	—	12	18		V_{GE} = 15V
$t_{d(on)}$	Turn-On Delay Time	—	23	—	ns	
t_r	Rise Time	—	26	—		T_J = 25°C
$t_{d(off)}$	Turn-Off Delay Time	—	93	140		I_C =5.0A, V_{CC} = 960V
t_f	Fall Time	—	270	400		V_{GE} = 15V, R_G = 50Ω
E_{on}	Turn-On Switching Loss	—	0.45	—	mJ	Energy losses include "tail"
E_{off}	Turn-Off Switching Loss	—	0.44	—		See Fig. 9,10,14
E_{ts}	Total Switching Loss	—	0.89	1.2		
t_{sc}	Short Circuit Withstand Time	10	—	—	µs	V_{CC} = 720V, T_J = 125°C
						V_{GE} = 15V, R_G = 50Ω
$t_{d(on)}$	Turn-On Delay Time	—	23	—	ns	T_J = 150°C,
t_r	Rise Time	—	28	—		I_C = 5.0A, V_{CC} = 960
$t_{d(off)}$	Turn-Off Delay Time	—	100	—		V_{GE} = 15V, R_G = 50Ω
t_f	Fall Time	—	620	—		Energy losses include "tail"
E_{ts}	Total Switching Loss	—	1.7	—	mJ	See Fig. 10,11,14
L_E	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package
C_{ies}	Input Capacitance	—	435	—	pF	V_{GE} = 0V
C_{oes}	Output Capacitance	—	44	—		V_{CC} = 30V See Fig. 7
C_{res}	Reverse Transfer Capacitance	—	8.3	—		f = 1.0MHz

Notes:

① Repetitive rating; V_{GE} = 20V, pulse width limited by max. junction temperature. (See fig. 13b)

② V_{CC} = 80%(V_{CES}), V_{GE} = 20V, L = 10µH, R_G =50Ω, (See fig. 13a)

③ Repetitive rating; pulse width limited by maximum junction temperature.

④ Pulse width ≤ 80µs; duty factor ≤ 0.1%.

⑤ Pulse width 5.0µs, single shot.

* When mounted on 1" square PCB (FR-4 or G-10 Material). This is applied for D^2pak
For recommended footprint and soldering techniques refer to application note #AN-994.

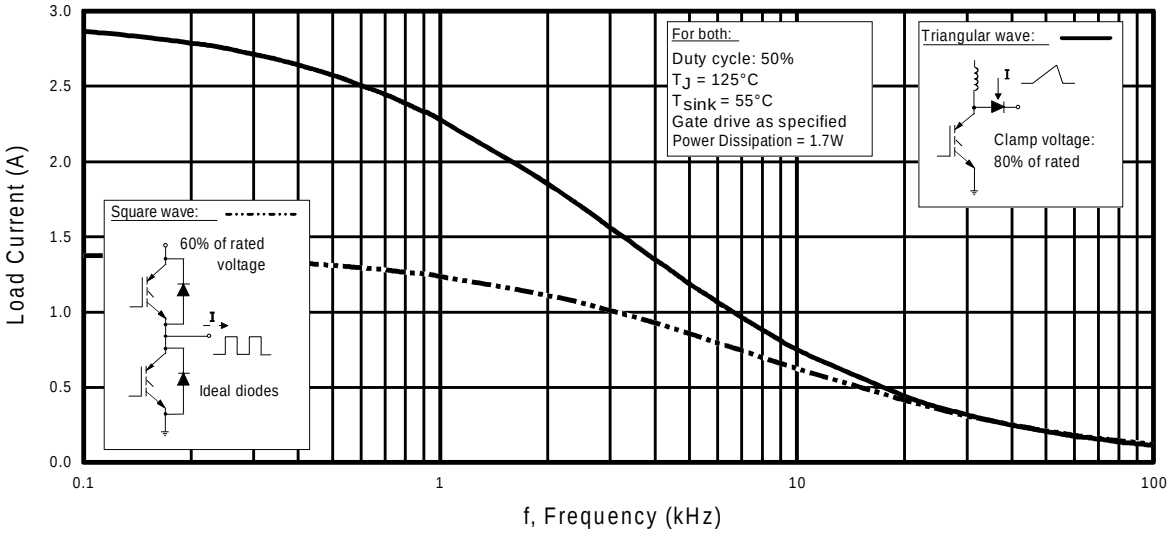


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

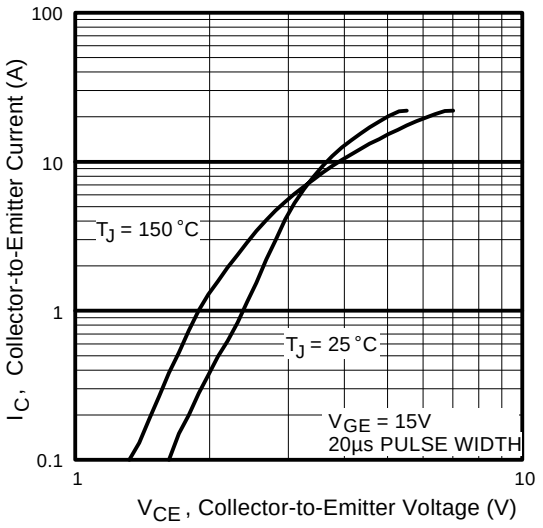


Fig. 2 - Typical Output Characteristics

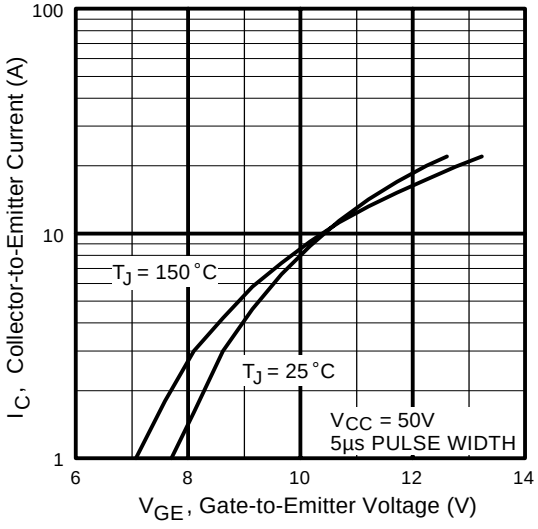


Fig. 3 - Typical Transfer Characteristics

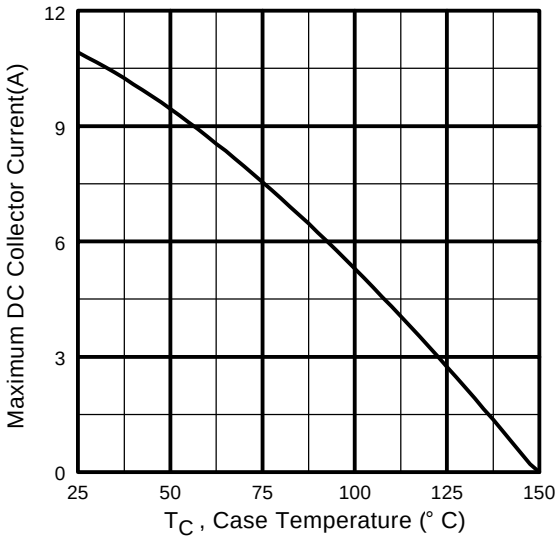


Fig. 4 - Maximum Collector Current vs. Case Temperature

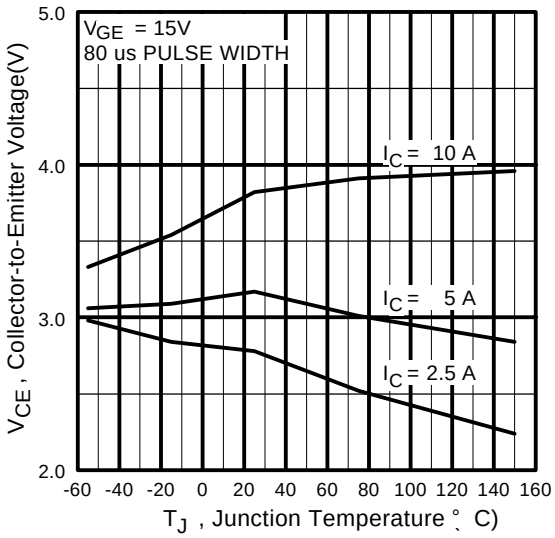


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

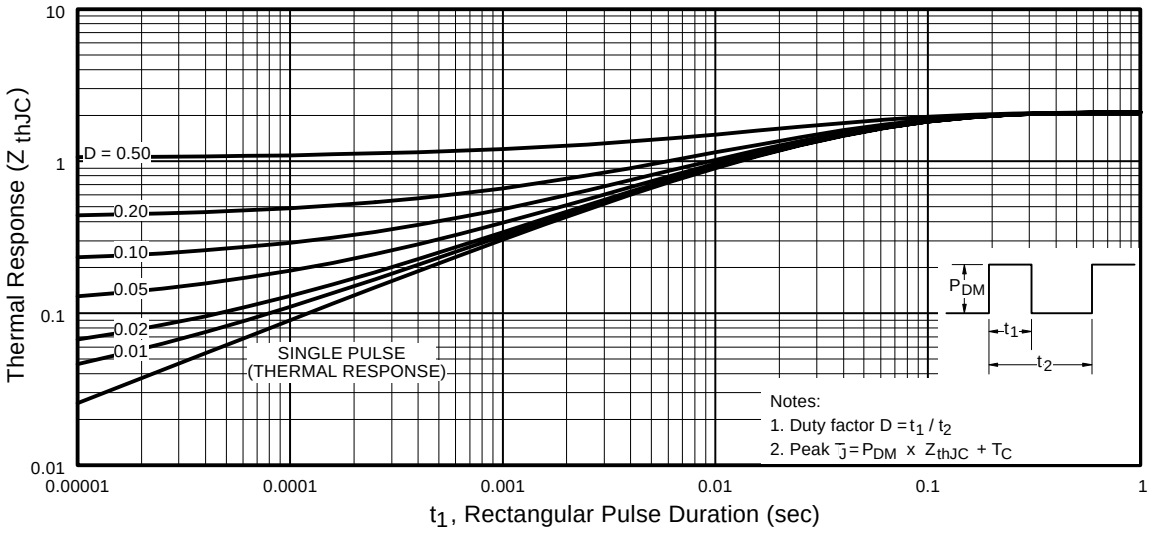


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

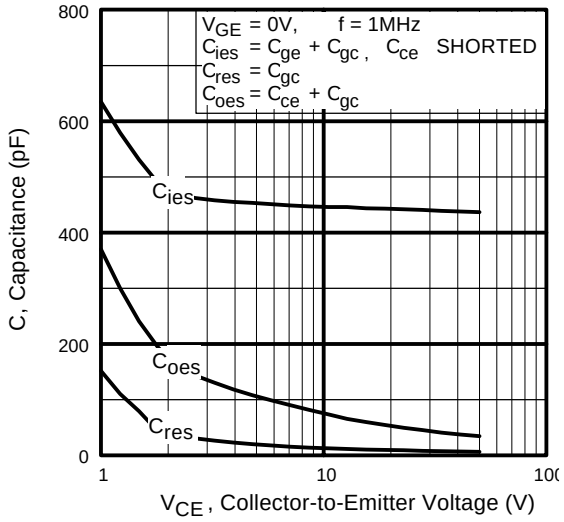


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

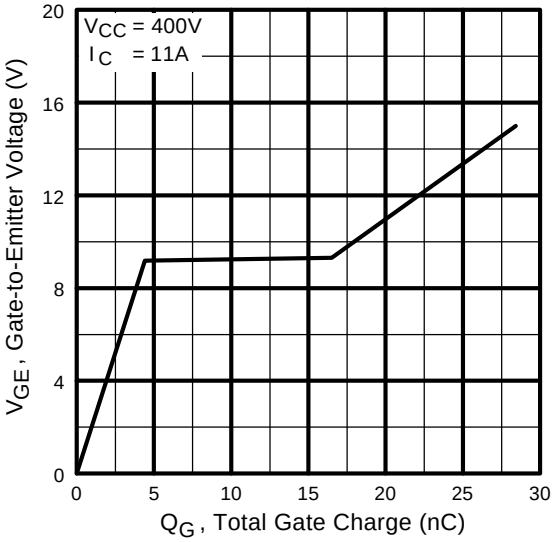


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

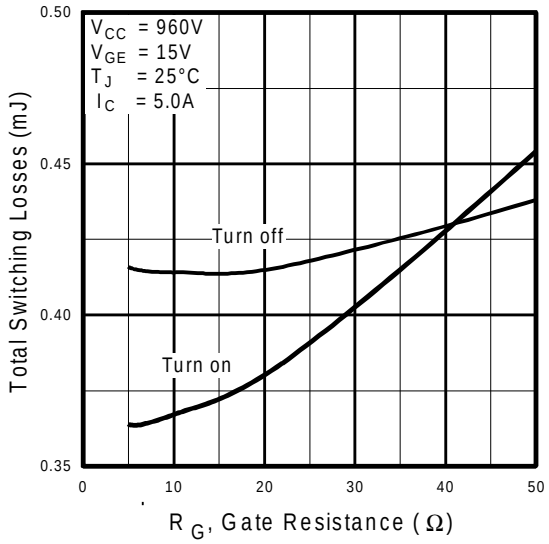


Fig. 9 - Typical Switching Losses vs. Gate Resistance

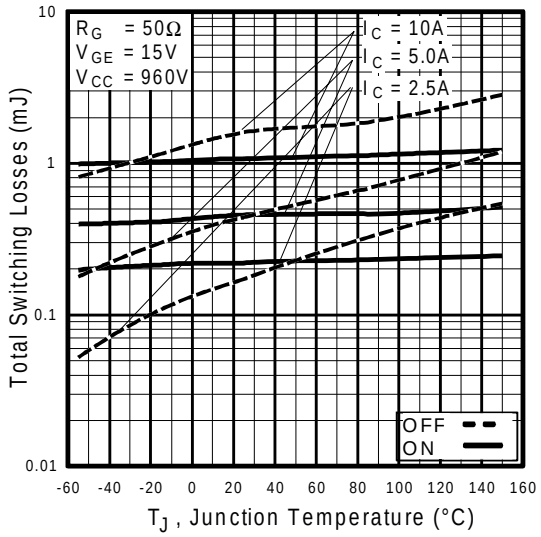


Fig. 10 - Typical Switching Losses vs. Junction Temperature

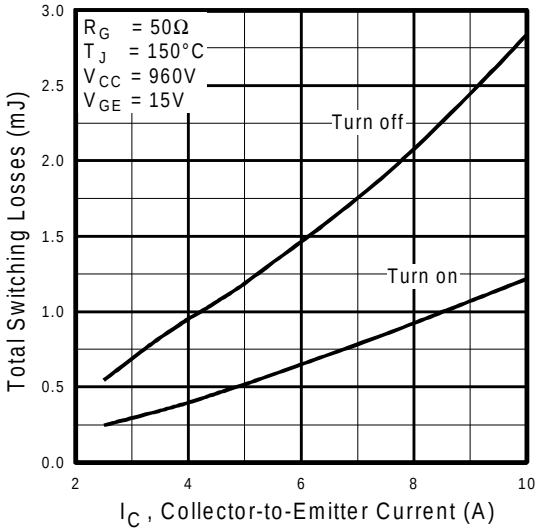


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

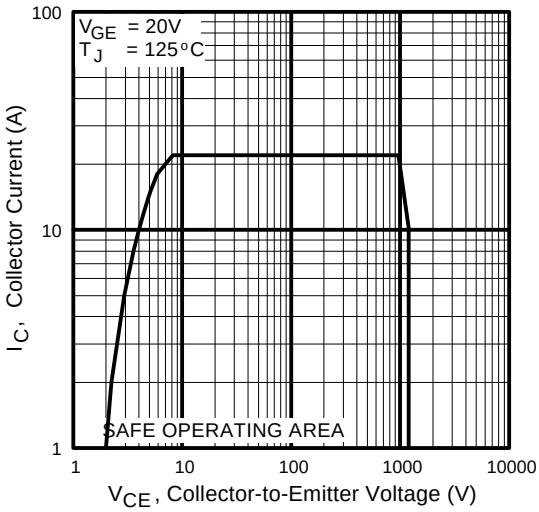


Fig. 12 - Turn-Off SOA

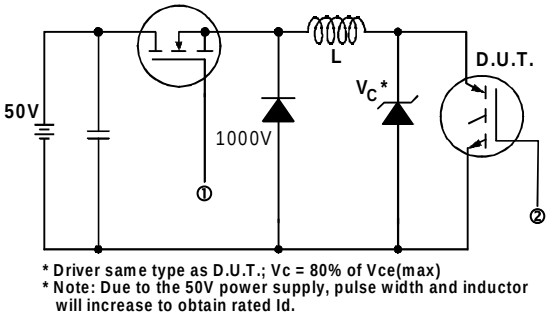


Fig. 13a - Clamped Inductive Load Test Circuit

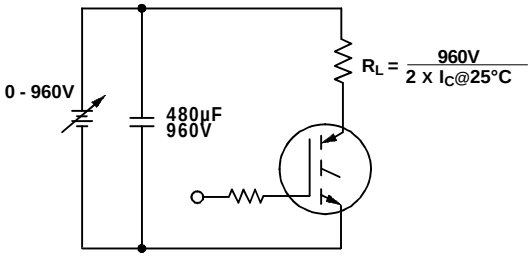


Fig. 13b - Pulsed Collector Current Test Circuit

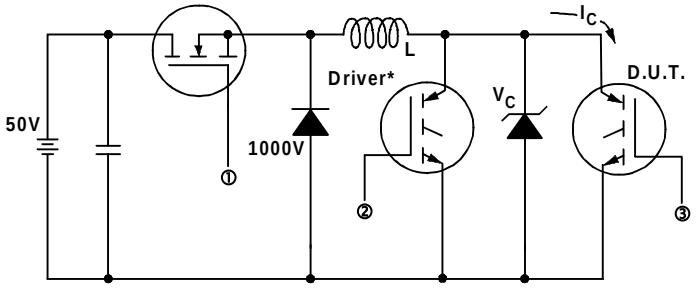


Fig. 14a - Switching Loss Test Circuit

*** Driver same type as D.U.T., VC = 960V**

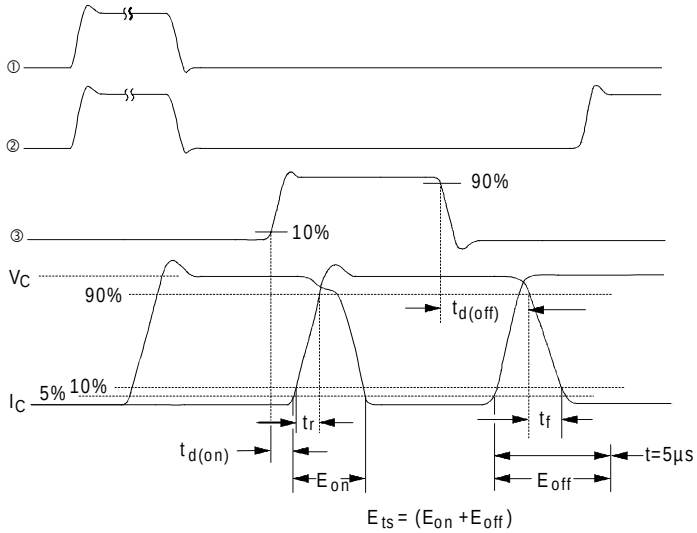
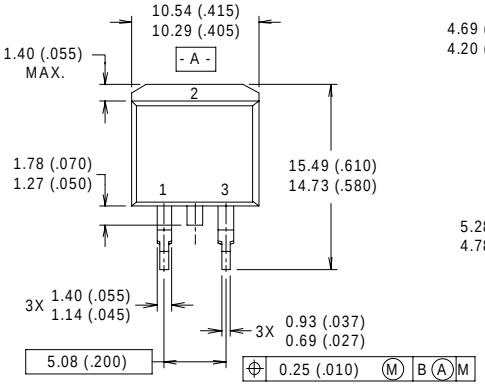
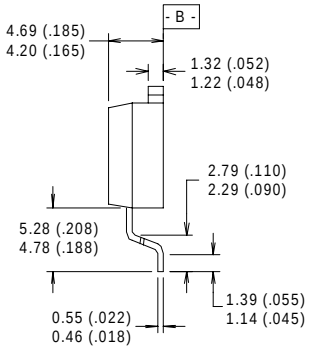


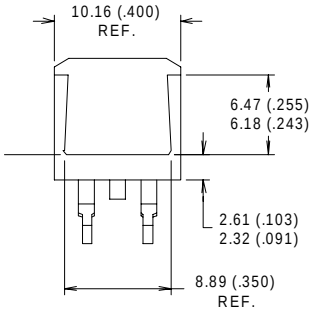
Fig. 14b - Switching Loss Waveforms

TO-263 IRG4BH20K-S,
TO-262 IRG4BH20K-L

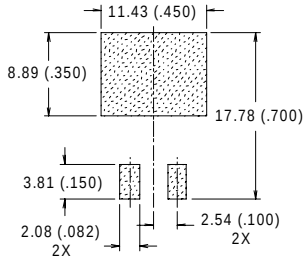
D²Pak Package Details







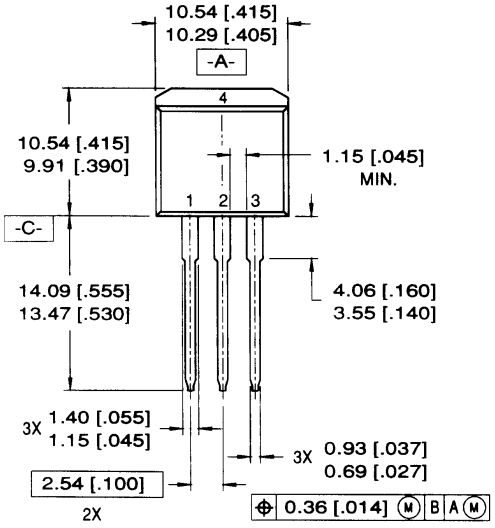
MINIMUM RECOMMENDED FOOTPRINT

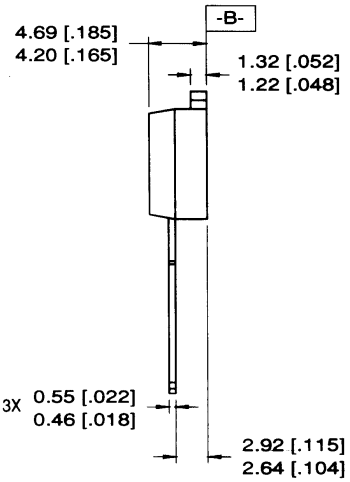


NOTES:
1 DIMENSIONS AFTER SOLDER DIP.
2 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
3 CONTROLLING DIMENSION : INCH.
4 HEATSINK & LEAD DIMENSIONS DO NOT INCLUDE BURRS.

LEAD ASSIGNMENTS
1 - GATE
2 - DRAIN
3 - SOURCE

TO-262 Package Details





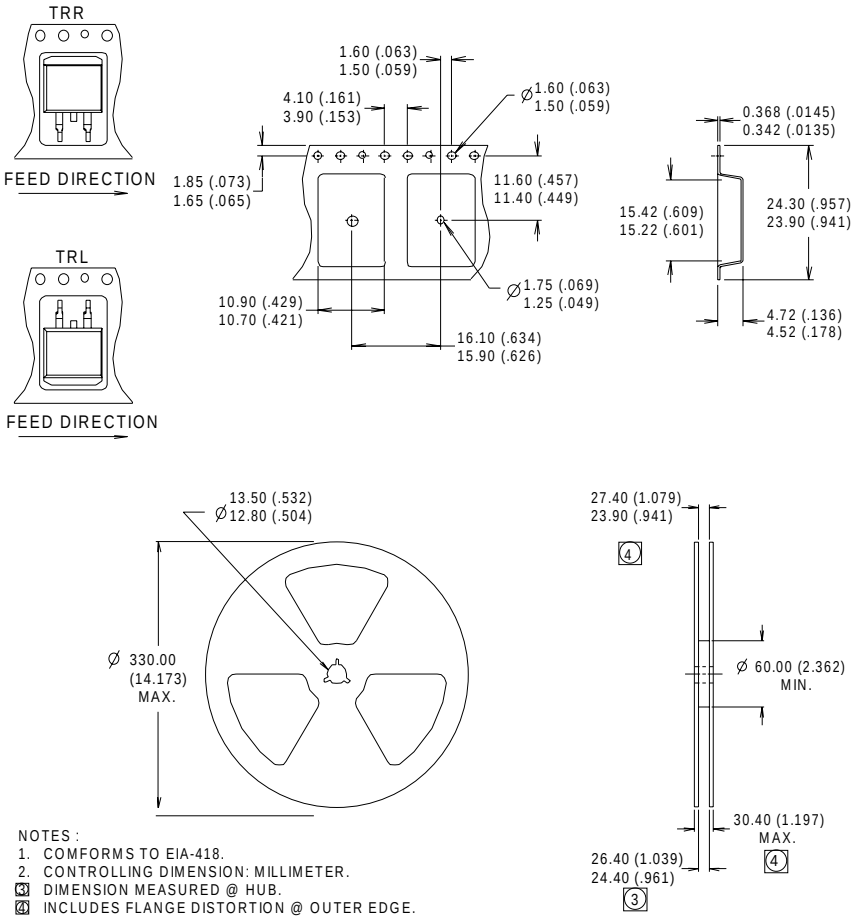
LEAD ASSIGNMENTS

1 = GATE 3 = SOURCE
2 = DRAIN 4 = DRAIN

NOTES:

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. HEATSINK & LEAD DIMENSIONS DO NOT INCLUDE BURRS.

D²Pak Tape and Reel



NOTES :
1. COMFORMS TO EIA-418.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION MEASURED @ HUB.
4. INCLUDES FLANGE DISTORTION @ OUTER EDGE.

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